

ABSTRACT OF THE DISCLOSURE

A heat dissipation system for a semiconductor device having a plurality of semiconductor chips, includes a heat dissipation member which cools the semiconductor chips, an exterior heat dissipation member which is provided opposite to the heat dissipation member, engaged to the semiconductor device and connected to an electrical ground, an electric conductor member which is provided between the heat dissipation member and the exterior heat dissipation member, and electrically connects the heat dissipation member and the exterior heat dissipation member to each other, and a thermal conductivity insulating member which is inserted between the heat dissipation member and the exterior heat dissipation member. Accordingly, the resistance against common mode noise is increased. Furthermore, the heat dissipation efficiency of the semiconductor device is also increased. The head dissipation system improves the heat dissipation efficiency of the semiconductor device to control noise.